



Customer Information Notification

202002035I

Issue Date: 26-Feb-2020
Effective Date: 27-Feb-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

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QUALITY

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - Data Sheet Update - Clarifications | | | |

HB2000 Data Sheet Update to Rev 8.0 (General and 28-pin HVQFN Clarifications)

Description

NXP Semiconductors announces the data sheet update to revision 8.0 for the HB2000 devices associated with this notification. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

Data Sheet Changes:

1. Global: changed document status from Advance Information to Product
2. Table 1: replaced "PC33HB2000ES" by "MC33HB2000AES"
3. Figure 5: updated 28-pin HVQFN pin configuration to indicate four corner pads as AGND
4. Section 9.6.3.1: added steps to clear the status register
5. Section 10.4.1.6: added note about minimum current for active OL detection
6. Section 12.1: added 28-pin HVQFN solder mask information

** Documentation change only for customer clarifications - absolutely no changes to the device / product **

New HB2000 rev 8.0 data sheet is attached to this notice, and can be found at:
<https://www.nxp.com/docs/en/data-sheet/MC33HB2000.pdf>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheet has been updated to provide additional technical clarifications regarding fault clearing, minimum requirements for active open load detection, and 28-pin HVQFN corner pad labels and solder mask diagram.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MC33HB2000FK	935312664557	MC33HB2000FK	H-Bridge DC Motor Dr	SOT1633-1	HQFN32	RFS	Driver & Energy Systems